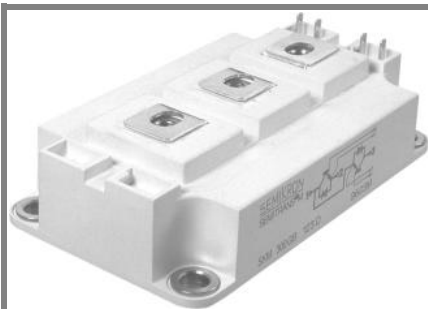


SKM 150GB128D



SEMITRANS® 3

SPT IGBT Modules

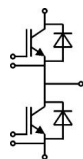
SKM 150GB128D

Features

- SPT = Soft punch-through technology
- V_{CEsat} with positive temperature coefficient
- High short circuit capability, self limiting to $6 \times I_C$

Typical Applications

- AC inverter drives
- UPS
- Electronic welders at f_{sw} up to 20 kHz

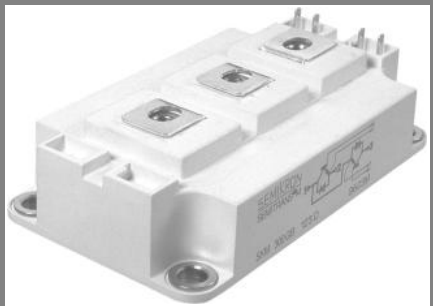


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Absolute Maximum Ratings			$T_c = 25\text{ }^{\circ}\text{C}$, unless otherwise specified	
Symbol	Conditions		Values	Units
IGBT				
V_{CES}	$T_j = 25\text{ }^{\circ}\text{C}$		1200	V
I_C	$T_j = 150\text{ }^{\circ}\text{C}$	$T_c = 25\text{ }^{\circ}\text{C}$	200	A
		$T_c = 80\text{ }^{\circ}\text{C}$	140	A
I_{CRM}	$I_{CRM}=2 \times I_{Cnom}$		200	A
V_{GES}			± 20	V
t_{psc}	$V_{CC} = 600\text{ V}; V_{GE} \leq 20\text{ V}; T_j = 125\text{ }^{\circ}\text{C}$ $V_{CES} < 1200\text{ V}$		10	μs
Inverse Diode				
I_F	$T_j = 150\text{ }^{\circ}\text{C}$	$T_{case} = 25\text{ }^{\circ}\text{C}$	150	A
		$T_{case} = 80\text{ }^{\circ}\text{C}$	100	A
I_{FRM}	$I_{FRM}=2 \times I_{Fnom}$		200	A
I_{FSM}	$t_p = 10\text{ ms}; \sin.$	$T_j = 150\text{ }^{\circ}\text{C}$	1100	A
Module				
$I_{t(RMS)}$			500	A
T_{vj}			- 40... + 150	$^{\circ}\text{C}$
T_{stg}			- 40... + 125	$^{\circ}\text{C}$
V_{isol}	AC, 1 min.		4000	V

Characteristics			T _c = 25 °C, unless otherwise specified			
Symbol	Conditions		min.	typ.	max.	Units
IGBT						
V _{GE(th)}	V _{GE} = V _{CE} , I _C = 4 mA		4,5	5,5	6,5	V
I _{CES}	V _{GE} = 0 V, V _{CE} = V _{CES} T _j = 25 °C			0,2	0,6	mA
V _{CE0}				1	1,15	V
				0,9	1,05	V
r _{CE}	V _{GE} = 15 V T _j = 25°C			9	12	mΩ
				12	15	mΩ
V _{CE(sat)}	I _{Cnom} = 100 A, V _{GE} = 15 V T _j = 25°C _{chiplev.}			1,9	2,35	V
				2,1	2,55	V
C _{ies}	V _{CE} = 25, V _{GE} = 0 V f = 1 MHz			8,1		nF
C _{oes}				1,2		nF
C _{res}				1,1		nF
Q _G	V _{GE} = -8V - +20V			1200		nC
R _{Gint}	T _j = 25 °C			2,5		Ω
t _{d(on)}	R _{Gon} = 8 Ω	V _{CC} = 600V I _C = 100A		80		ns
t _r				40		ns
E _{on}				10		mJ
t _{d(off)}	R _{Goff} = 8 Ω	T _j = 125 °C V _{GE} = ±15V		460		ns
t _f				65		ns
E _{off}				9		mJ
R _{th(j-c)}	per IGBT				0,15	K/W

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Typical Applications

- AC inverter drives
- UPS
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Characteristics					
Symbol	Conditions	min.	typ.	max.	Units
Inverse Diode					
$V_F = V_{EC}$	$I_{Fnom} = 100\text{ A}; V_{GE} = 0\text{ V}$				
	$T_j = 25\text{ }^{\circ}\text{C}_{chiplev.}$		2	2,5	V
	$T_j = 125\text{ }^{\circ}\text{C}_{chiplev.}$		1,8	2,3	V
V_{F0}					
	$T_j = 25\text{ }^{\circ}\text{C}$		1,1	1,45	V
	$T_j = 125\text{ }^{\circ}\text{C}$			1,25	V
r_F					
	$T_j = 25\text{ }^{\circ}\text{C}$		9	13	mΩ
	$T_j = 125\text{ }^{\circ}\text{C}$			11	mΩ
I_{RRM}	$I_F = 100\text{ A}$		145		A
Q_{rr}	$di/dt = 3600\text{ A}/\mu\text{s}$		16,5		μC
E_{rr}	$V_{GE} = -15\text{ V}; V_{CC} = 600\text{ V}$		5,5		mJ
$R_{th(j-c)D}$	per diode			0,3	K/W
Module					
L_{CE}			15	20	nH
$R_{CC'+EE'}$	res., terminal-chip				
	$T_{case} = 25\text{ }^{\circ}\text{C}$		0,35		mΩ
	$T_{case} = 125\text{ }^{\circ}\text{C}$		0,5		mΩ
$R_{th(c-s)}$	per module			0,038	K/W
M_s	to heat sink M6	3		5	Nm
M_t	to terminals M6	2,5		5	Nm
w				325	g

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.



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